V_{CC}

19 OE2

18**∏** Y1

17 TY2

16 TY3

15**∏** Y4 14 TY5

13**∏** Y6

12 ¶ Y7

11 Y8

DW OR N PACKAGE

(TOP VIEW)

OE1

A1 2

A2 3

АЗ [

Α4 5

A5

А6 Г

А8 Г 9

Α7 8

GND []

4

10

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- 3-State Outputs Drive Bus Lines or Buffer **Memory Address Registers**
- pnp Inputs Reduce dc Loading
- Outputs Have 25-Ω Series Resistor So No External Resistors Are Required
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

description

This octal line driver/MOS driver is designed to drive the capacitive input characteristics of MOS devices and to have the performance of the

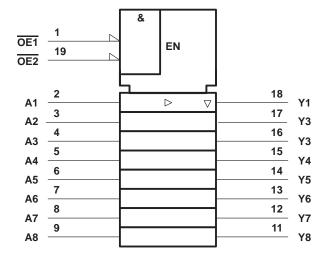
popular SN74ALS240 series. At the same time, this device offers a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly facilitates printed-circuit-board layout.

The 3-state output-control gate is a 2-input NOR. If either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state.

The SN74ALS2541 provides true data at the outputs.

The SN74ALS2541 is characterized for operation from 0°C to 70°C.

logic symbol†

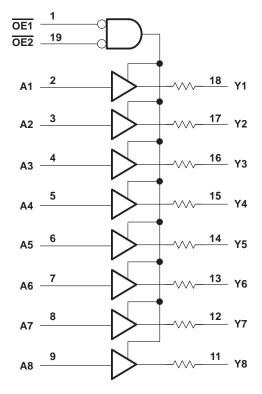


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



All output resistors are 25 Ω .

absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			8.0	V
IOH	High-level output current			-0.4	mA
l _{OL}	Low-level output current			12	mA
TA	Operating free-air temperature	0		70	°C



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COND	DITIONS	MIN TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	I _I = -18 mA		-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2		V
	V 45V	I _{OL} = 1 mA	0.15	0.5	V
V _{OL}	$V_{CC} = 4.5 \text{ V}$	I _{OL} = 12 mA	0.35	0.8	V
IOZH	$V_{CC} = 5.5 V,$	V _O = 2.7 V		20	μΑ
lozL	$V_{CC} = 5.5 V,$	V _O = 0.4 V		-20	μΑ
ГОН	$V_{CC} = 4.5 V,$	V _O = 2 V	-15		mA
IOL	$V_{CC} = 4.5 V,$	V _O = 2 V	30		mA
lį	V _{CC} = 5.5 V,	V _I = 7 V		0.1	mA
lін	V _{CC} = 5.5 V,	V _I = 2.7 V		20	μΑ
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V		-0.1	mA
IO [‡]	V _{CC} = 5.5 V,	V _O = 2.25 V	-15	-70	mA
		Outputs high	6	14	
ICC	V _{CC} = 5.5 V	Outputs low	15	25	mA
		Outputs disabled	13.5	22	

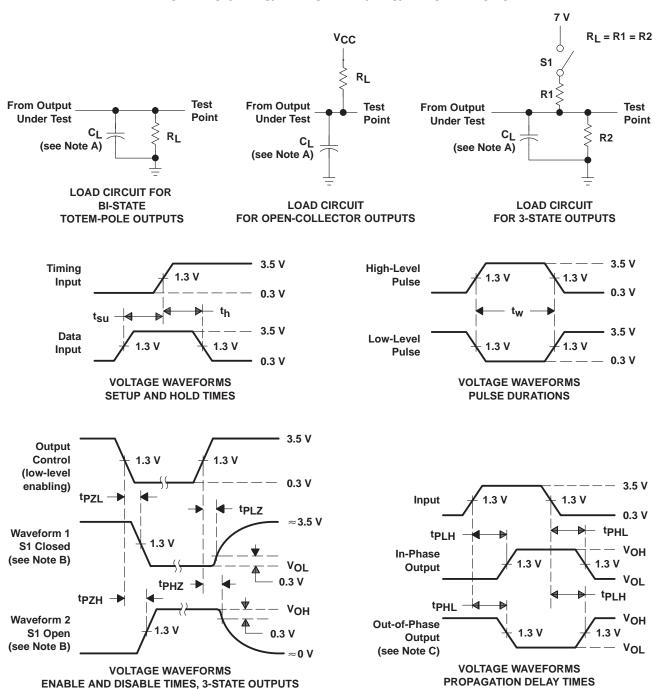
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5$ $C_L = 50 \text{ pF}$ $R1 = 500 \Omega$ $R2 = 500 \Omega$ $T_A = MIN \text{ to}$; , ,	UNIT
			MIN	MAX	
^t PLH	•	V	2	15	
t _{PHL}	A	Y	2	12	ns
^t PZH	ŌĒ	V	5	15	
tPZL	OE	Y	8	20	ns
^t PHZ	ŌĒ	V	1	10	
t _{PLZ}	OE .	Y	2	12	ns

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[†] All typical values are V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 - D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_{\Gamma} = t_{f} = 2$ ns, duty cycle = 50%.
 - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS2541DW	OBSOLETE	SOIC	DW	20		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS2541NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS2541NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS2541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS2541NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS2541DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS2541NSR	SO	NS	20	2000	346.0	346.0	41.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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